



GP
ELECTRONICS

GPT025N04LTB
40V N-Channel MOSFET

Product Summary

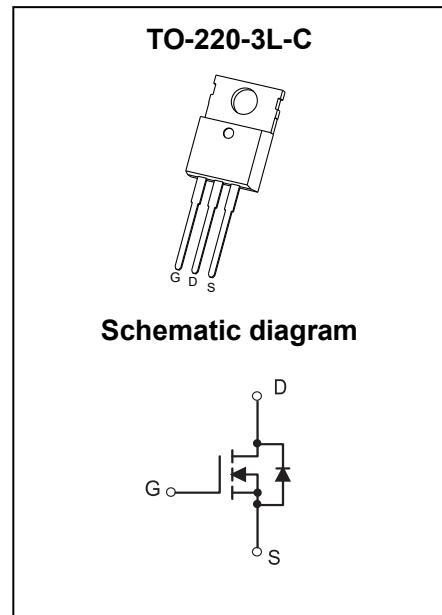
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	1.7mΩ@10V	120A
	1.9mΩ@6V	

Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application



MARKING:



025N04L = Device Code

XX = Date Code

Solid Dot = Green Indicator

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	40	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	120	A
Continuous Drain Current ¹	I_D	80	A
Pulsed Drain Current ²	I_{DM}	480	A
Single Pulsed Avalanche Current ³	I_{AS}	38	A
Single Pulsed Avalanche Energy ³	E_{AS}	735	mJ
Power Dissipation ⁵	P_D	156	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	60	°C/W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.8	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

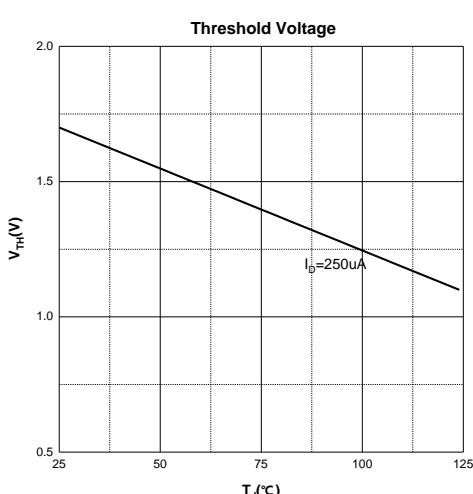
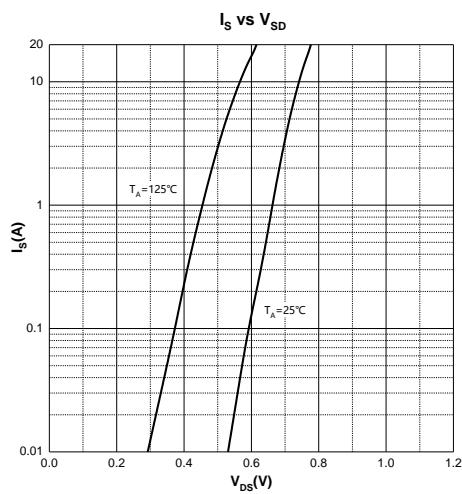
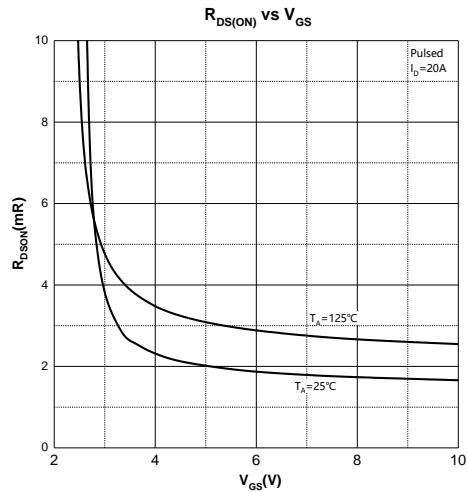
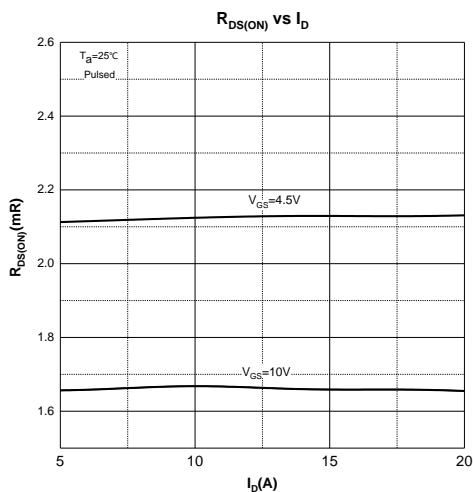
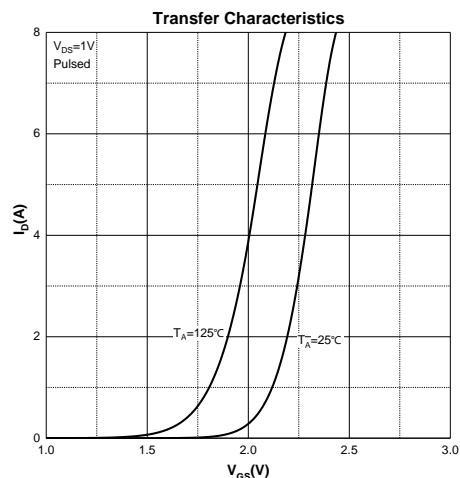
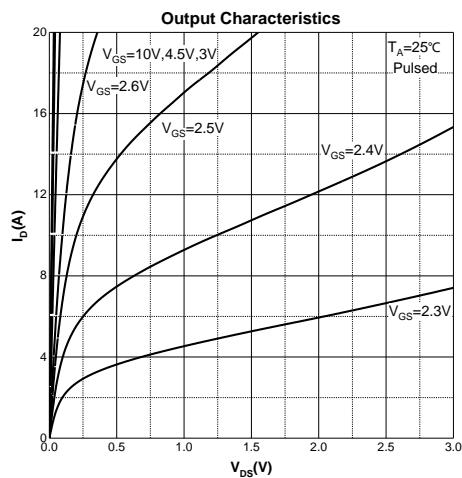
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

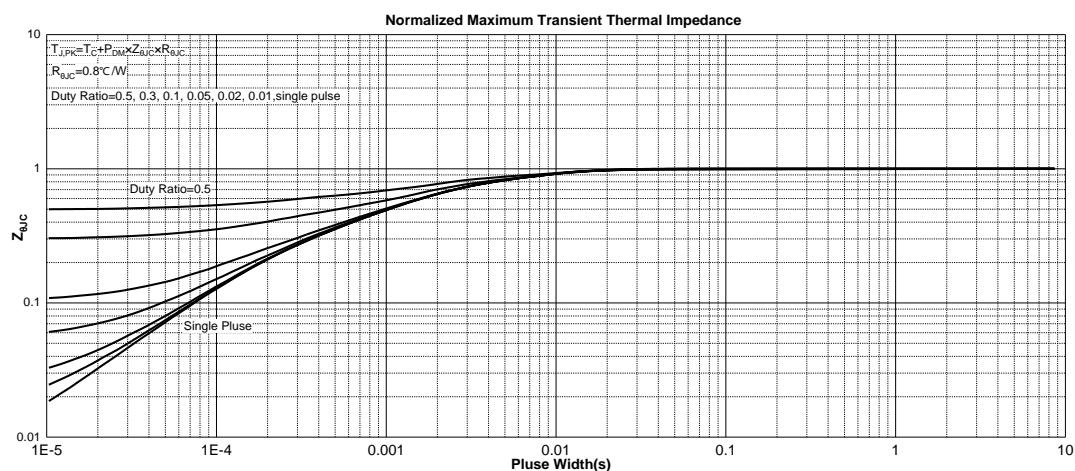
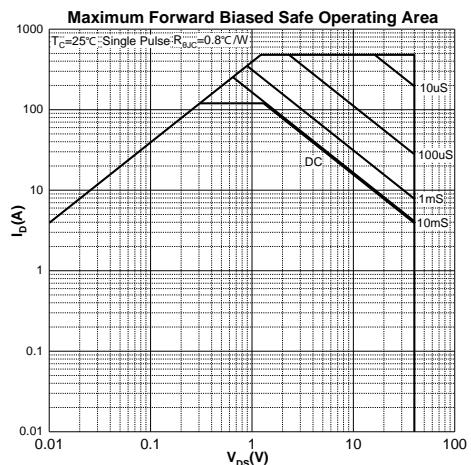
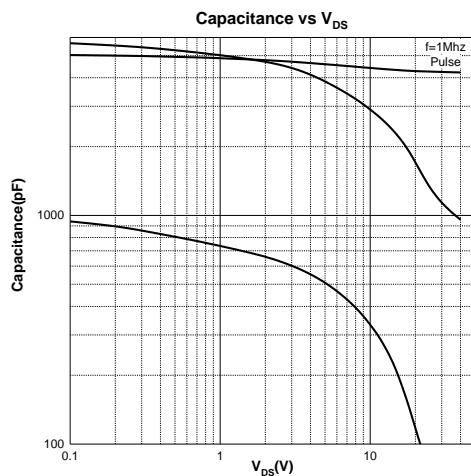
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.7	3.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		1.7	2.5	$\text{m}\Omega$
		$V_{\text{GS}} = 6\text{V}, I_D = 20\text{A}$		1.9	3.0	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$	50			S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		4279		pF
Output Capacitance	C_{oss}			1744		
Reverse Transfer Capacitance	C_{rss}			118		
Gate Resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		65		nC
Gate-source Charge	Q_{gs}			15		
Gate-drain Charge	Q_{gd}			5.2		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, R_L = 1\Omega$ $R_G = 3\Omega$		12		ns
Turn-on Rise Time	t_r			9		
Turn-off Delay Ttime	$t_{\text{d}(\text{off})}$			52		
Turn-off Fall Time	t_f			15		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 20\text{A}$			1.2	V

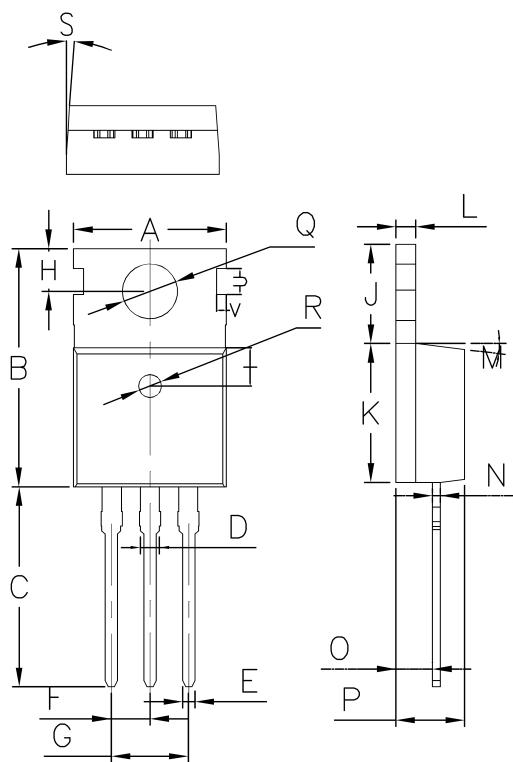
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{\text{DD}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, L = 1\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics





TO-220-3L-C Package Information


Symbol	Min	Non	Max
A	9.80	10.00	10.20
B	15.40	15.60	15.80
C	13.02	13.37	13.72
D	1.18	1.31	1.44
E	0.70	0.80	0.90
F	2.42	2.54	2.66
G	4.84	5.08	5.32
H	2.73	2.80	2.87
I	2.40	2.50	2.60
J	6.40	6.50	6.60
K	9.00	9.10	9.20
L	1.29	1.30	1.32
M	6.5°	7.0°	7.5°
N	0.48	0.50	0.56
O	2.35	2.4	2.5
P	4.4	4.5	4.7
Q	3.5	3.6	3.7
R	1.3	1.4	1.5
S	2°	2.5°	3°
U	1.65	1.75	1.85
V	0.58	0.68	0.78